

ACC MICRO 2016 BUFFER AND MUX LOGIC

DATA BOOK

MARCH 1997 Revision 2.0

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Appendix A-1 List of Sales Representatives

ACC Micro 2016 Buffer and MUX Logic

Section 1 Introduction

1.1 Description

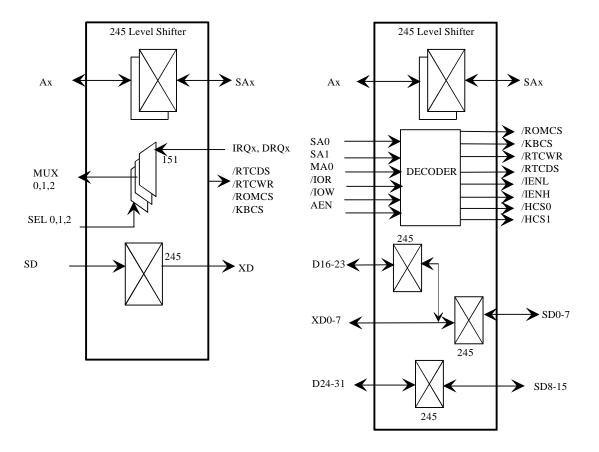
The ACC Micro 2016 is designed to work together with the system core logic products to provide the decoding logic for the Real Time Clock (RTC), address buffer, and data buffer for the 486/386DX and Pentium applications. At least seven TTLs can be saved when using the 2016.

1.2 Features

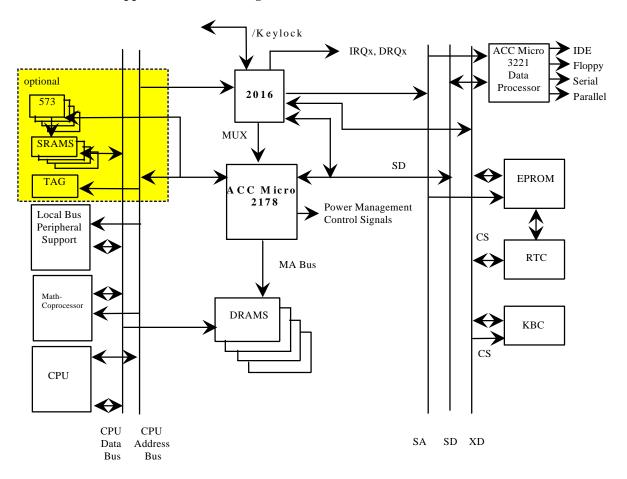
- ♦ Address Buffer
- ♦ Data Buffer
- ♦ Decode logic for /ROMCS, /KBCS, /RTCWR, and /RTCDS
- ♦ Saved up to 7 TTLs
- ♦ 100-pin PQFP and TQFP

1.3.1 2016 Internal Block Diagram with 2268/2178/2168/2056/2057/2066/2048 System Logic

1.3.2 2016 Internal Block Diagram with 2086/2087/2089 System Logic



1.4 2016/2178 Application Circuit Diagram



Section 2 Functional Description

The 2016 can be used with either the 2268/2178/2168/2056/2057/2066/2048 system logic or the 2086/2087/2089 super chip. The 2016 is based on the condition of the /ROMCS signal to determine which system logic to work with. During power up, if the /ROMCS is pulled high, it works with the 2268/2178/2168/2056/2057/2066/2048 system logic. If /ROMCS is pulled low, it works with the 2086/2087/2089 super chip. The /RTCDS signal (pin 97) requires a pull low through a damping register for all system logic applications.

Section 3.0 Pin Description

3.1 2268/2178/2168/2056/2057/2066/2048 System Logic

Table 3.1.1 Address Buffer Signals

Pin Name	Pin #	Type	Description
A2-A16	2531,33-40	I/O	Local Address Bus
SA2-SA16	6-13,15,17-22	I/O	System Address Bus
/ENABUS	24	I	Address bus buffer

Table 3.1.2 Data Buffer Signals

Pin Name	Pin #	Type	Description
SD0-SD7	73-80	I/O	System Data Bus
XD0-XD7	81-89	I/O	XD Bus
/XDIR	62	I	XD bus direction control

Table 3.1.3 Multiplexer Signals

Pin Name	Pin #	Type	Description
MUXO0-	42-44	О	Multiplexed output for KBINT, IRQ3-9, and /RTCINT.
MUXO2			Multiplexed output for IRQ10-15, KGA20, and /IOCHK.
			Multiplexed output for DRQ0-3, DRQ5-7, and /KBRST.
SEL0-SEL2	45-47	I	Multiplexer select pins for MUXO0-MUXO2.
IRQ3-IRQ7	48-52	I	RTC interrupt.
IRQ9,	53		
/RTCINT	55		
IRQ10-IRQ13	56-58		
DRQ6-7	59-60	I	DMA request.
/KBCS	61	О	Keyboard chip select.
IRQ14-IRQ15	63-64	I	Interrupt
/IOCHK	65		
DRQ0-DRQ3	66-68, 71		
DRQ5	72		
/IOCHK	65	I	I/O channel check DMA request.
DRQ0-DRQ3	66-68, 71		
DRQ5	72		

Table 3.1.4 MA Mux Signals

Pin Name	Pin #	Type	Description
MA0	23	I	MA0 from ACC Micro system logic. In AT cycle, this is a
			multiplexed pin for /ROMCS.
/ROMCS	92	I/O	ROM Chip Select output. Pulled high.
/RTCWR	96	О	RTC Write output.
/RTCDS	97	I/O	RTC Data Strobe output.
/KGA20	2	I/O	Keyboard GA20 input
/KBRST	3	I/O	Keyboard reset input.
KBINT	98	I/O	Keyboard interrupt input.
IRQ12	99	I/O	Interrupt request.

Table 3.1.5 AT Bus Signals

Pin Name	Pin #	Type	Description
/IOR	93	I	AT Bus Read.
/IOW	94	I	AT Bus Write.
AEN	95	I	Bus Hold Acknowledge
/MASTER	100	I	AT Bus Master
/REF	1	I	Refresh Cycle.
SA0	4	I	System Address Bit 0.
SA1	5	I	System Address Bit 1.

Table 3.1.6 RESET Signal

Pin Name	Pin #	Type	Description
/RST	91	I	Chip reset.

Table 3.1.7 Power Signals

Pin Name	Pin #	Type	Description
VDD	16, 32, 54, 69,	P	5V power.
	90		
GND	14, 41, 70, 88	P	Ground.

3.2 2086/2087/2089 System Logic

Table 3.2.1 Address Buffer Signals

Pin Name	Pin #	Type	Description
A2-A16	2531,33-40	I/O	Local Address Bus
SA2-SA16	6-13,15,17-22	I/O	System Address Bus
/ENABUS	24	I	Address bus buffer

Table 3.2.2 Data Buffer Signals

Pin Name	Pin #	Type	Description
SD0-SD7	73-80	I/O	System Data Bus
XD0-XD7	81-89	I/O	XD Bus
/XDIR	62	I	XD bus direction control

Table 3.2.3 Multiplexer Signals

Pin Name	Pin #	Type	Description
D16-D31	42-53, 55-58	I/O	CPU Data Bus.
/ENSDL	59	I	SD Bus buffer low byte enable.
/ENSDH	60	I	SD Bus buffer high byte enable.
/SDDIR	61	I/O	SD Bus Direction control.
SD8-SD15	63-68, 71-72	I/O	System data bus.

Table 3.2.4 MA Mux Signals

Pin Name	Pin #	Type	Description
MA0	23	I	MA0 from ACC Micro system logic. In AT cycle, this is a
			multiplexed pin for /ROMCS.
/ROMCS	92	I/O	ROM Chip Select output. Pulled low.
/RTCWR	96	О	RTC Write output.
/RTCDS	97	I/O	RTC Data Strobe output.
/IENL	2	I/O	IDE data buffer low byte enable.
/IENH	3	I/O	IDE data buffer high byte enable.
/HCS0	98	I/O	IDE chip select bit 0.
/HCS1	99	I/O	IDE chip select bit 1.

Table 3.2.5 AT Bus Signals

Pin Name	Pin #	Type	Description
/IOR	93	I	AT Bus Read.
/IOW	94	I	AT Bus Write.
AEN	95	I	Bus Hold Acknowledge
/MASTER	100	I	AT Bus Master
/REF	1	I	Refresh Cycle.
SA0	4	I	System Address Bit 0.
SA1	5	I	System Address Bit 1.

Table 3.2.6 RESET Signal

Pin Name	Pin #	Type	Description
/RST	91	I	Chip reset.

Table 3.2.7 Power Signals

Pin Name	Pin #	Type	Description
VDD	16, 32, 54, 69,	P	5V power.
	90		
GND	14, 41, 70, 88	P	Ground.

Section 4.0 2016 DC Specifications

TA = 0° C to 45° C, $Vdd = 5.0V \pm 5\%$

Signals: AEN, MAO, SAO, SA1, /ENABUS, /IOR, /IOW, /REF, /MASTER, /XDIR, DRQ6, DRQ7

Parameter	Sym.	Min.	Max.	Unit	Test Condition
Input low voltage	VIL		0.8	V	$Vdd = 5.0 \pm 5\%$
Input high voltage	VIH		2.0	V	$Vdd = 5.0 \pm 5\%$
Input low current	IIL		-10.0	uA	Vin = 0.0V
Input high current	IIH		10.0	uA	Vin = Vdd

Signals: /RST

Parameter	Sym.	Min.	Max.	Unit	Test Condition
Threshold voltage low to high	VTLH	2.4	3.0	V	$Vdd = 5.0V \pm 5\%$
Threshold voltage high to low	VTLH	1.2	1.8	V	$Vdd = 5.0V \pm 5\%$
Hysteresis	VH	0.9	1.5	V	
Triput low Leakage Current	IIL		-10.0	uA	Vin = 0.0V
Input high Leakage Current	IIH		10.0	uA	Vin = 5.5V

Signals: /RTC

Parameter	Sym.	Min.	Max.	Unit	Test Condition
Output low voltage	VOL		0.4	V	IOL = 4.0 mA
Output high voltage	VOH	2.4		V	IOH = 4.0 mA
Tristate Output Leakage	IOZ	-10.0	10.0	uA	0V < Vout < Vdd
Current					

Signals: A2-A16, MUX0-MUX2, SEL0-SEL2, IRQ3-IRQ7, IRQ9-IRQ13, /RTCINT, XD0-XD7, /ROMCS, /RTCDS, /KBCS

/ROMCS, /RTCDS, /KBCS

Parameter	Sym.	Min.	Max.	Unit	Test Condition
Input low voltage	VTL		0.8	V	$Vdd = 5.0V \pm 5\%$
Input high voltage	VIH	2.0		V	$Vdd = 5.0V \pm 5\%$
Input low current	IIL		-10.0	uA	VIN = 0.0V
Input high current	IIH		10.0	uA	VIN = Vdd
Output low voltage	VOL		0.4	V	IOL = 4.0 mA
Output high voltage	VOH	2.4		V	IOH = -4.0 mA
Tristate output leakage current	IOZ	-10.0	10.0	uA	0V < Vout < Vdd

Signals: KBINT, /KGA20, /KBRST

Parameter	Sym.	Min.	Max.	Unit	Test Condition
Input low voltage	VTL		0.8	V	$Vdd = 5.0 V \pm 5\%$
Input high voltage	VIH	2.0		V	$Vdd = 5.0 V \pm 5\%$
Input low current	IIL		-10.0	uA	VIN = 0.0V
Input high current	IIH		10.0	uA	VIN = Vdd
Output low voltage	VOL		0.4	V	IOL = 4.0 mA
Output high voltage	VOH	2.4		V	IOH = -4.0 mA
Tristate output leakage current	IOZ	-10.0	10.0	uA	0V < Vout < Vdd

Signals: SA2-SA16, SD0-SD7

Parameter	Sym.	Min.	Max.	Unit	Test Condition
Input low voltage	VIL		0.8	V	$Vdd = 5.0V \pm 5\%$
Input high voltage	VIH	2.0		V	$Vdd = 5.0V \pm 5\%$
Input low current	IIL		-10.0	uA	VIN = 0.0V
Input high current	IIH		10.0	uA	VIN = Vdd
Output low voltage	VOL		0.4	V	IOL = 4.0 mA
Output high voltage	VOH	2.4		V	IOH = -4.0 mA
Tristate output leakage current	IOZ	-10.0	10.0	uA	0V < Vout < Vdd

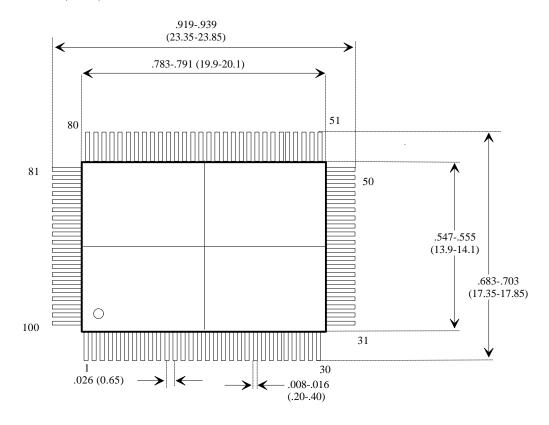
Signals: IRQ14, IRQ15, /IOCHK, DRQ0-DRQ3, DRQ5

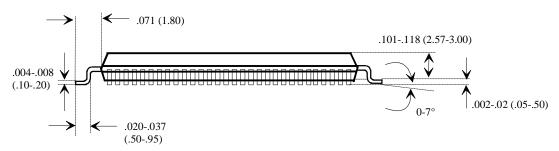
Parameter	Sym.	Min.	Max.	Unit	Test Condition
Input low voltage	VIL		0.8	V	$Vdd = 5.0V \pm 5\%$
Input high voltage	VIH	2.0		V	$Vdd = 5.0V \pm 5\%$
Input low current	IIL		-10.0	uA	VIN = 0.0V
Input high current	IIH		10.0	uA	VIN = Vdd
Output low voltage	VOL		0.4	V	IOL = 4.0 mA
Output high voltage	VOH	2.4		V	IOH = -4.0 mA
Tristate output leakage current	IOZ	-10.0	10.0	uA	0V < Vout < Vdd

Section 5 Package Specifications

5.1 100-pin PQFP Package Specification

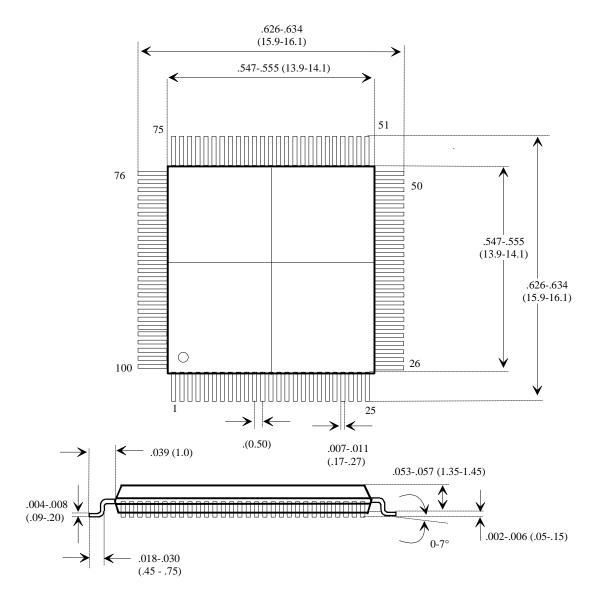
Unit: inches (mms.)





5.2 100-pin TQFP Package Specification

Unit: inches (mms.)





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